

Product Change Notification / ASER-28RAPG851

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10-Jan-2023

Product Category:

Power Management - System Supervisors/Voltage Detectors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5128 Final Notice: Qualification of a new lead frame design and G700 as a new mold compound material for selected MIC277xxx device family available in 5L SOT-23 package assembled at STAR assembly site.

Affected CPNs:

ASER-28RAPG851_Affected_CPN_01102023.pdf ASER-28RAPG851_Affected_CPN_01102023.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of a new lead frame design and G700 as a new mold compound material for selected MIC277xxx device family available in 5L SOT-23 package assembled at STAR assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Stars Microelectronics (Thailand) Public Company Limited (STAR)	Stars Microelectronics (Thailand) Public Company Limited (STAR)
Wire Material	Au	Au
Die Attach Material	84-1LMISR4	84-1LMISR4
Molding Compound Material	G600	G700
Lead-Frame Material	C194	C194
DAP Surface Prep	NiPdAu with Roughened See Pre and Post Change	NiPdAuAg with Roughened Summary for comparison.

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity by qualifying a new lead frame design and G700 mold compound.

Change Implementation Status:In Progress

Estimated First Ship Date: February 10, 2023 (date code: 2306)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

		Ma	ay 20	22		>		Janu	ary 2	2023		Fel	orua	ry 20)23
Workweek	1 9	2	2 1	2	2		1	2	3	4	5	6	7	8	9
Initial PCN Issue Date	Х														
Qual Report Availability								Х							
Final PCN Issue Date								Х							
Estimated Implementation												Х			

Date								

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:May 3, 2022: Issued initial notification.

January 10, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on February 10, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN ASER-28RAPG851_Qual Report.pdf PCN_ASER-28RAPG851_Pre and Post Change Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

ASER-28RAPG851 - CCB 5128 Final Notice: Qualification of a new lead frame design and G700 as a new mold compound material for selected MIC277xxx device family available in 5L SOT-23 package assembled at STAR assembly site.

Affected Catalog Part Numbers (CPN)

MIC2774H-17YM5-TR

MIC2774H-22YM5-TR

MIC2774H-25YM5-TR

MIC2774H-28YM5-TR

MIC2774H-29YM5-TR

MIC2774H-44YM5-TR

MIC2774L-17YM5-TR

MIC2774L-22YM5-TR

MIC2774L-23YM5-TR

MIC2774L-25YM5-TR

MIC2774L-28YM5-TR

MIC2774L-29YM5-TR

MIC2774L-31YM5-TR

MIC2774L-44YM5-TR

MIC2774L-46YM5-TR

MIC2774N-17YM5-TR

MIC2774N-22YM5-TR

MIC2774N-23YM5-TR

MIC2774N-25YM5-TR

MIC2774N-28YM5-TR

MIC2774N-29YM5-TR

MIC2774N-31YM5-TR

MIC2774N-44YM5-TR

MIC2775-17YM5-TR

MIC2775-22YM5-TR

MIC2775-23YM5-TR

MIC2775-25YM5-TR

MIC2775-26YM5-TR

MIC2775-28YM5-TR

MIC2775-29YM5-TR

MIC2775-31YM5-TR

MIC2775-44YM5-TR

MIC2775-46YM5-TR MIC2776L-YM5-TR

MIC2776N-YM5-TR

MIC2777-17YM5-TR

MIC2777-22YM5-TR

MIC2777-23YM5-TR

MIC2777-25YM5-TR

MIC2777-26YM5-TR

MIC2777-28YM5-TR

MIC2777-29YM5-TR

MIC2777-31YM5-TR

MIC2777-44YM5-TR

MIC2775-29YM5-TX

MIC2774H-23YM5-TR

Date: Tuesday, January 10, 2023

ASER-28RAPG851 - CCB naterial for selected MIC27	5128 Final Notice: Qualificat 7xxx device family available	tion of a new lead frame in 5L SOT-23 package	e design and G700 as a new e assembled at STAR asser	w mold compound mbly site.
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MIC2774N-46YM5-TR				
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/IC2774N-29YM5-TX				
MIC2776L-YM5-TX				
/IIC2776N-YM5-TX				
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Date: Tuesday, January 10, 2023